

# Evolution of the Wafer-level Characterization Solutions: Towards mmW 6G Applications

Vince Mallette, Dr Andrej Rumiantsev







## Outline

- Instrumentation Evolution
- Drivers and Challenges
- Next-Generation Characterization Systems and Components
- Differential and Multiport Characterization
- Conclusion

### Outline

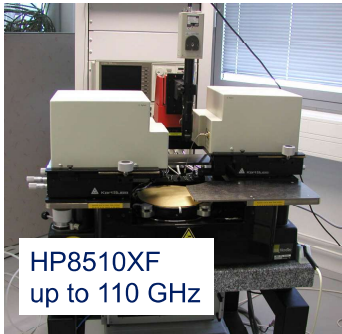
# Introduction: Instrumentation Evolution

## Instrumentation → Communication Enablers

| 1G  | 2G  |   | 3G  |  |   | 4G  |                        | 5G  |                                 | 6G  |
|---|---|---|---|--|---|---|------------------------|---|---------------------------------|---|
|  |  |   |    |  |   |  |                        |  |                                 |  |
|   | Up to 1.9 GHz   |   | Up to 2.1 GHz   |  |   | Up to 2.5 GHz   |                        | Up to 95 GHz  |                                 | Up to THz   |
| 1G  | 2G  | 2½G   | 3G  | 3½G  | 3¾G                                     | 4G  | 4½G                    | 5G  | 5G adv.                         | 6G  |
| 1981  | 1990  | 1993  | 2001  | 2006   | 2010                                    | 2015  | 2018                   | 2020  | 2024                            | 2030  |
| C-Net<br>NMT<br>AMPS<br>TACS  | GSM <sup>1</sup><br>CDMA IS-95A   | GPRS <sup>2</sup><br>IS-95B                       | EDGE <sup>3</sup><br>UMTS <sup>4</sup><br>CDMA 2000   | HSDPA <sup>5</sup><br>HSPA+<br>1xEV-DO         | LTE <sup>6</sup><br>Rel.8               | LTE-A <sup>7</sup><br>Rel.10  | LTE-A Pro<br>Rel.13/14 | LTE / NR <sup>8</sup><br>Rel.15/16/17   | LTE / NR <sup>8</sup><br>Rel.18 |   |
|   | <sup>1</sup> GSM<br>Global System for Mobile Communication                            | <sup>2</sup> GPRS<br>General Packet Radio Service | <sup>3</sup> EDGE<br>Enhanced Data Rate for Global Evolution<br><sup>4</sup> UMTS<br>Universal Mobile Telecommunications System | <sup>5</sup> HSDPA<br>High Speed Packet Access | <sup>6</sup> LTE<br>Long Term Evolution | <sup>7</sup> LTE Advanced   |                        | <sup>8</sup> NR<br>New Radio  | <sup>8</sup> NR<br>New Radio    |   |

On the Road to 6G: Drivers, Challenges, and Enabling Technologies, A Fraunhofer 6G white paper, Fraunhofer, Nov. 2021, 15pp.

## Broadband Instrumentation Evolution



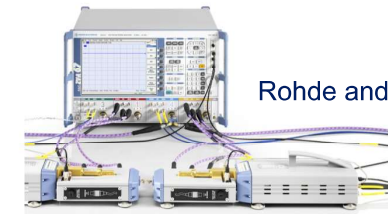
1999: Single Sweep  
Development of accurate device models

## Broadband Instrumentation Evolution

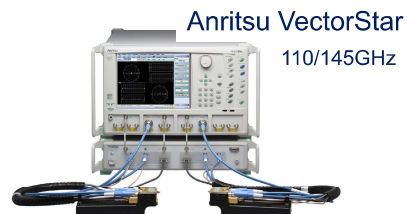


2000s: Size reduction

- Integration of other instrumentation (Load pull, ect.)
- Complex IC development
- Differential mmW



## Broadband Instrumentation Evolution



2010s: Further Size reduction and band expansion

- Characterization accuracy
- Differential mmW
- 145 GHz



## Broadband Instrumentation Evolution



2020s: Further Size reduction and band expansion

- 220 GHz
- 220 GHz differential
- D-band complex systems



<https://www.keysight.com/ca/en/assets/3121-1515/technical-overviews/170GHz-220GHz-Broadband-Vector-Network-Analysis-Solution.pdf>

## Broadband Instrumentation Evolution



2020s: Further Size reduction and band expansion

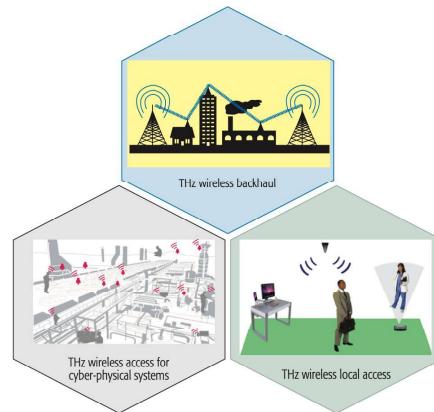
- 220 GHz
- 220 GHz differential
- D-band complex systems



## Drivers and Challenges

## Example: 6G Drivers and Challenges

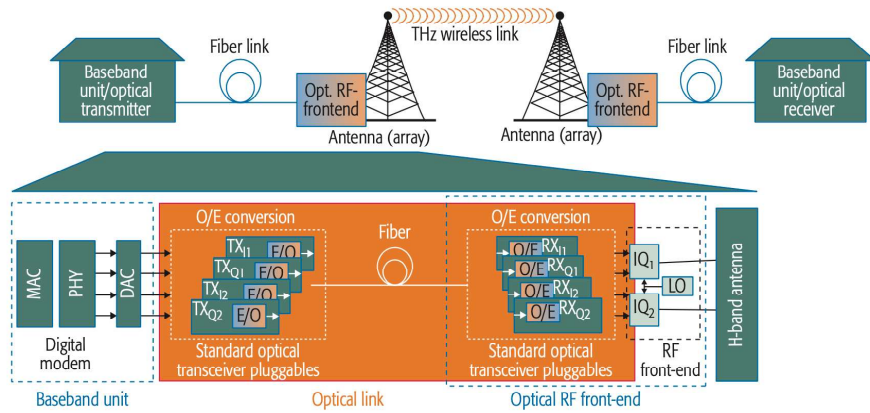
- THz wireless backhaul
- THz wireless access for cyber-physical systems
- THz wireless local access



## 6G Drivers and Challenges

*The key driver for 6G will remain **the extended network capacity**. And this can be achieved only through **new, Terahertz (THz) spectrum-based technologies**. Be it capacities of 4 Tbit/s for AR/XR, the under 100  $\mu$ s delay for industrial or holographic presence, a 7-nines reliability, or < 1 cm-precision localization.*

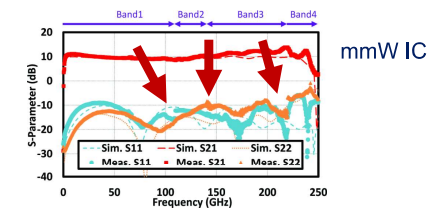
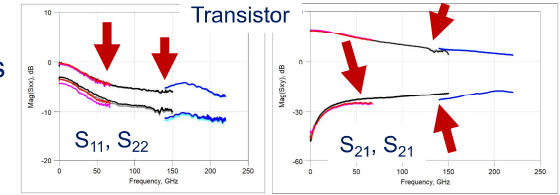
# 6G Challenges: Broadband Front-Ends



A. -A. A. Boulogeorgos et al., "Terahertz Technologies to Deliver Optical Network Quality of Experience in Wireless Systems Beyond 5G", in IEEE Communications Magazine, vol. 56, no. 6, pp. 144-151, June 2018

# Challenge: Broadband Data Inconsistency

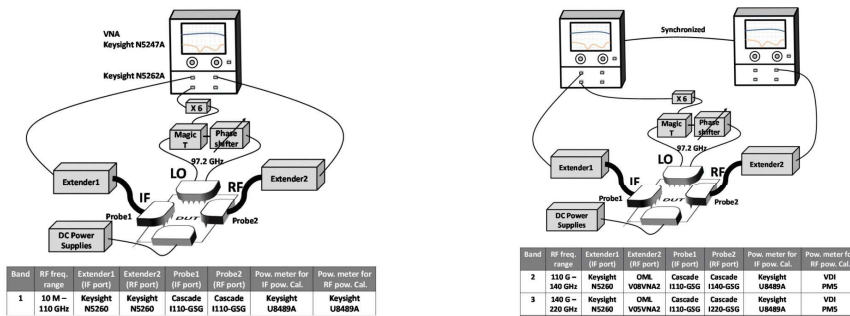
- Measurement data analysis and interpretation challenges increase with the number of frequency bands
- Sources of errors:
  - Frequency extenders
  - Wafer probe designs
  - Calibration methods
  - Measurement repeatability



T. Jyo et al., "A 241-GHz-Bandwidth Distributed Amplifier with 10-dBm P1dB in 0.25- $\mu$ m InP DHBT Technology," IMS, 2019.

# Challenge: Setup Complexity & Reconfiguration

## Conversion gain characterization



T. Jyo et al., "A DC to 194-GHz Distributed Mixer in 250-nm InP DHBT Technology," 2020 IEEE/MTT-S International Microwave Symposium (IMS), 2020, pp. 771-774

# Next-Generation Characterization Systems

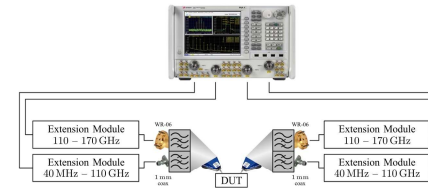


## Broadband Measurement Systems: 110GHz +

- Instrumentation versatility
- Probe system integration complexity
- Probes
- Calibration standards
- Metrological solutions
- Single-ended for device characterization
- Differential for IC validation

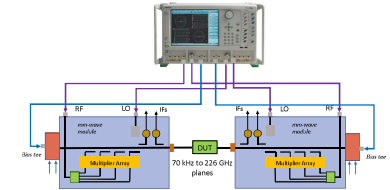
## Instrumentation: Two Approaches

### Conventional Instrumentation



- Two VNA Extenders
- DC to 170 GHz or to 220 GHz with WR5 and 120...140 GHz transition
- RF probe with 1mm, WR5 interfaces and an embedded combiner

### Next-Generation Instrumentation



- One broadband frequency extender
- DC to 226 GHz
- RF probe with 0.6 mm broadband interface

F. Boes, G. Gramlich, M. Kretschmann, S. Marahrens, and T. Zwick, "Ultrabroadband Diplexers for Next-Generation High-Frequency Measurement Applications," IEEE Transactions on Microwave Theory and Techniques, vol. 68, no. 6, pp. 2161-2167, 2020  
 J. Martens and T. Roberts, "Broadband 220 GHz network analysis: structures and performance," 94th ARFTG Microwave Measurement Conference Digest, San Antonio, TX, 26-29, 2020.

## Different Goals

### Conventional Extenders



- Accumulate already existing PNA-X and WR6/WR5 extenders
- Purchase the probes, probe system adaptation

### Next-Generation Extenders

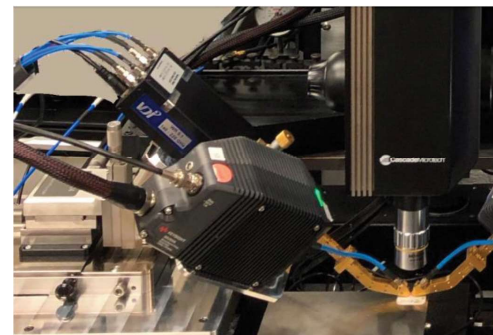


- Upgrade path of the existing VectorStar 110/145 GHz systems
- New measurement systems with future upgrade path

F. Boes, G. Gramlich, M. Kretschmann, S. Marahrens, and T. Zwick, "Ultrabroadband Diplexers for Next-Generation High-Frequency Measurement Applications," IEEE Transactions on Microwave Theory and Techniques, vol. 68, no. 6, pp. 2161-2167, 2020  
 J. Martens and T. Roberts, "Broadband 220 GHz network analysis: structures and performance," 94th ARFTG Microwave Measurement Conference Digest, San Antonio, TX, 26-29, 2020.

## Integration with the Probe System

### Conventional Extenders



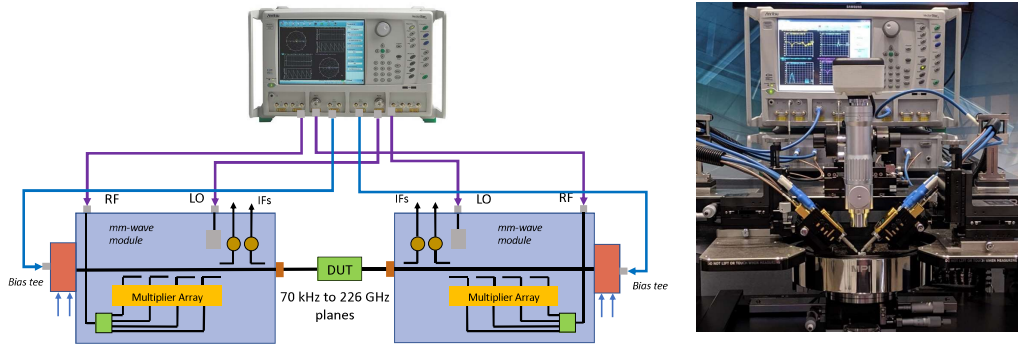
M. Bauers, A Dual-Band Probe for Ultra- Broadband Measurements, EuMW-2021

### Next-Generation Extenders



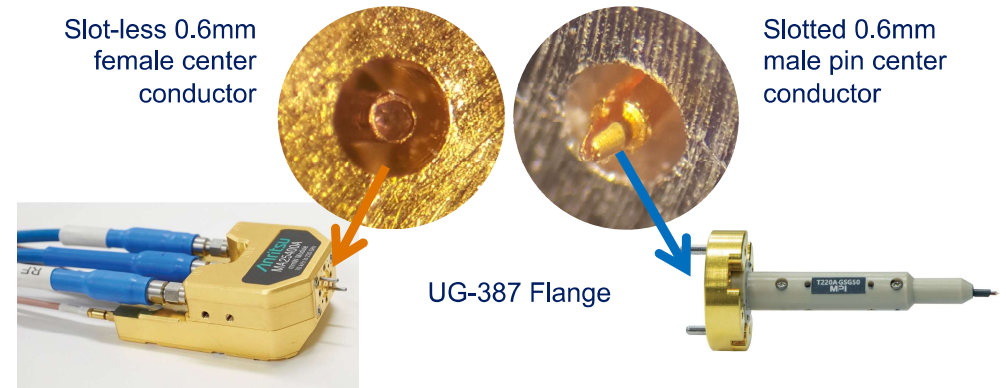
Pictures: DMPI, Anritsu

# Broadband 70 kHz-220 GHz Single-Sweep VNA



J. Martens and T. Roberts, "Broadband 220 GHz network analysis: structures and performance," 94th ARFTG Microwave Measurement Conference Digest, San Antonio, TX, 26-29 January, 2020.

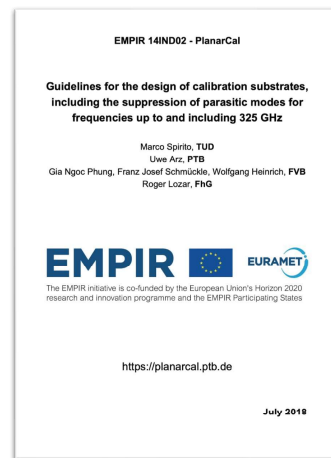
# Probe Interface with 220 GHz Module



A. Rumiantsev, et al, Calibration, Repeatability and Related Characteristics of On-wafer, Broadband 70 kHz-220 GHz Single-Sweep Measurements, ARFTG-95th

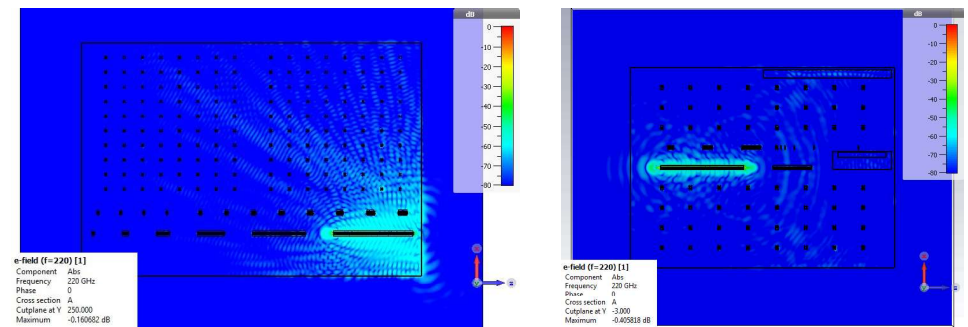
# Calibration Standards

Guidelines for the design of calibration substrates, including the suppression of parasitic modes for frequencies up to and including 325 GHz



# Minimized Coupling and Higher Order Modes: 220 GHz

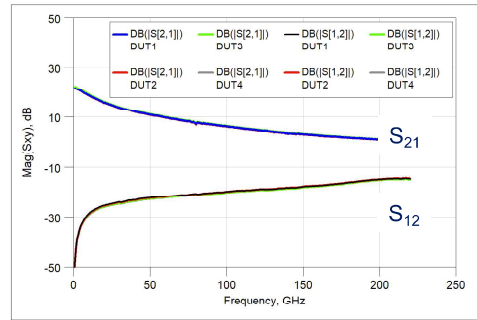
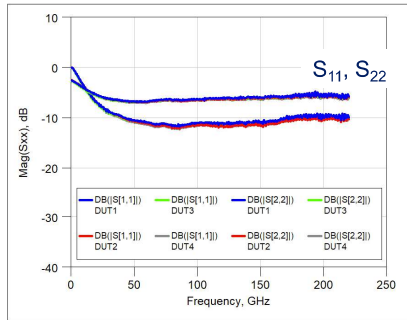
## Conventional vs optimized cal substrate



Rumiantsev, Andrej, Ralf Doerner, and Gia Ngoc Phung, "Calibration Substrate Design for Accurate Mm-Wave Probe-Tip Calibration." 94th ARFTG Microwave Measurement Conference, San Antonio, TX, 26-29 January, 2020.

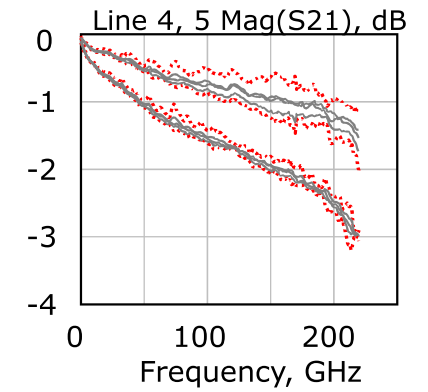
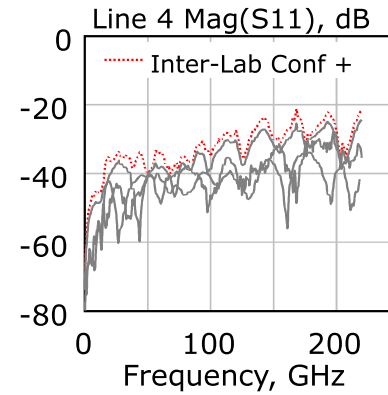
# Broadband Transistor Characterization

## Four devices, consistent results



Data courtesy: FBH

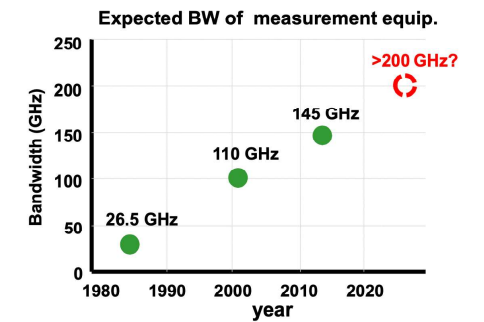
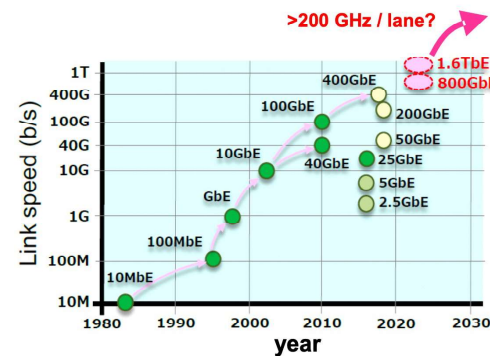
# Metrology: Inter-Laboratory Comparison



A. Rumiantsev, R. Doerner, J. Martens, and S. Reyes, "Inter-Laboratory Comparison of On-Wafer Broadband 70kHz-220GHz Single-Sweep Measurements," presented at the 2021 51st European Microwave Conference (EuMC)

# Differential and Multiport Characterization

## Required BW for DAC/ADC is Expected to Reach 200 GHz



## Differential design, characterization

Teruo Jyo, Munehiko Nagatani, Minoru Ida, Miwa Mutoh, Hitoshi Wakita, Naoki Terao, Hideyuki Nosaka A DC to 194-GHz Distributed Mixer in 250-nm InP DHBT Technology, IMS-2020, We3C-2

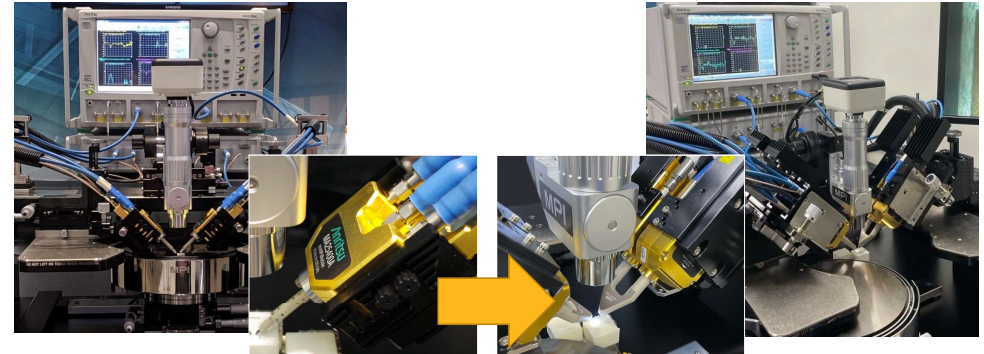


## Why Differential Broadband System?

One of the differential RF signals is terminated inside the chip for convenience of measurement **because a differential probe (GSGSG) above 110 GHz is unavailable\***.

\*T. Jyo et al., "A DC to 194-GHz Distributed Mixer in 250-nm InP DHBT Technology," 2020 IEEE/MTT-S International Microwave Symposium (IMS), 2020, pp. 771-774

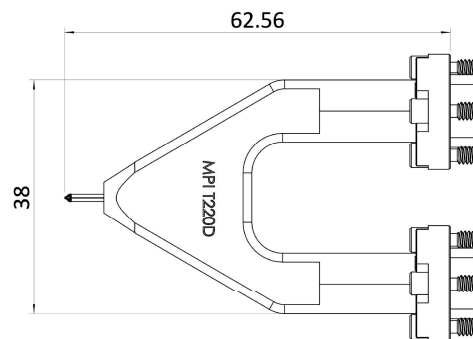
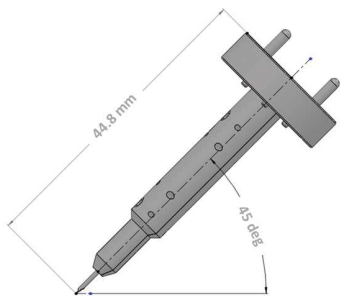
## Extension for Differential Measurements



## Only < 40% Longer than the Single-Ended Probe

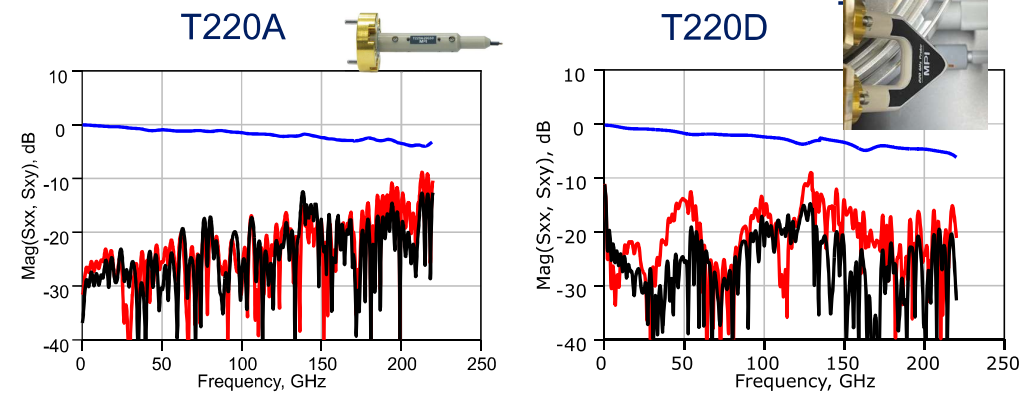
T220A: ~45 mm

T220D: ~63mm



A. Rumiantsev, J. Martens, S. Reyes, A Differential Broadband Single-Sweep 70 kHz-220 GHz Wafer-Level System: First Calibration and Measurement Characteristics, ARFTG-110<sup>th</sup>, 2023

## Insignificant Increase of the Probe Loss: < 1.7 dB@220 GHz

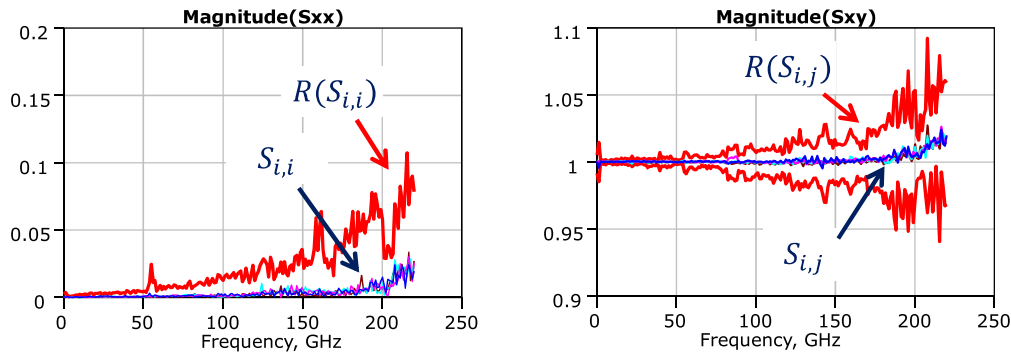


A. Rumiantsev, J. Martens, S. Reyes, A Differential Broadband Single-Sweep 70 kHz-220 GHz Wafer-Level System: First Calibration and Measurement Characteristics, ARFTG-110<sup>th</sup>, 2023



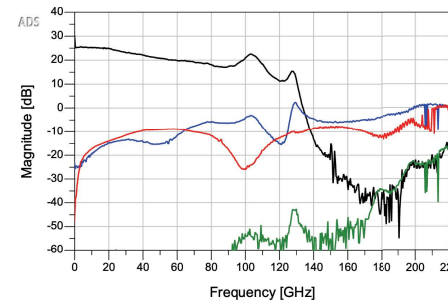
# First Step Towards Metrological Solution

Measurement Reproducibility Limit R: Thru

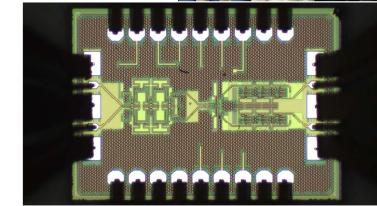
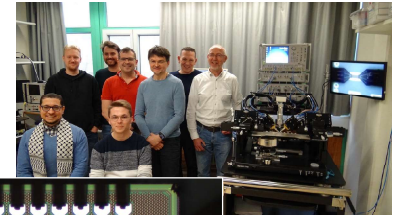


A. Rumiantsev, J. Martens, S. Reyes, A Differential Broadband Single-Sweep 70 kHz-220 GHz Wafer-Level System: First Calibration and Measurement Characteristics, ARFTG-110<sup>th</sup>, 2023

# Broadband mmWave Driver Circuit

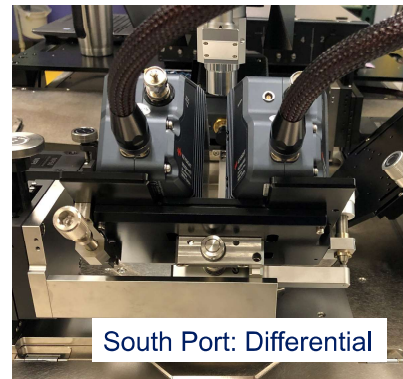
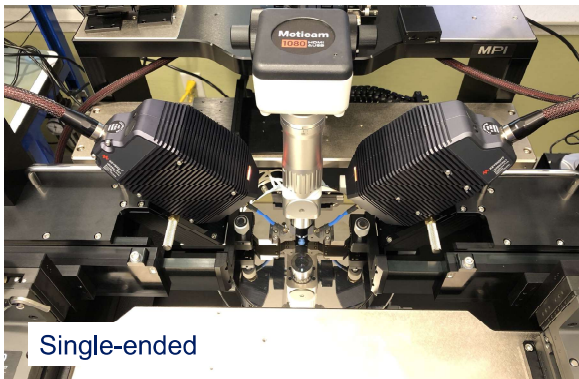


dB(S(2,1))  
dB(S(1,1))  
dB(S(2,2))  
dB(S(1,2))

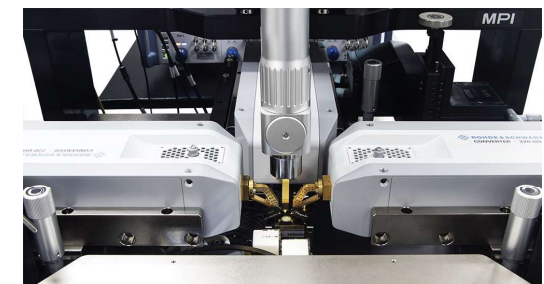
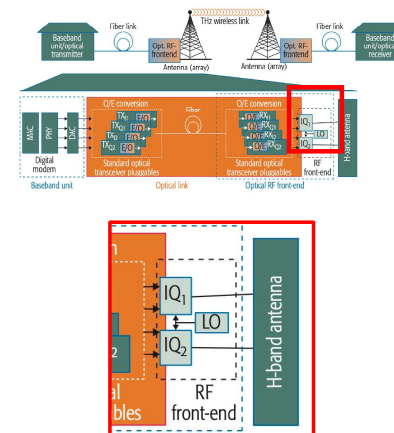


Courtesy: Ulm University, Germany

# Broadband Single-Ended and Differential Characterization



# Broadband Sub-Harmonic Mixer Characterization



Testing of the two-sided coupling energy of mmW and LO signals

## Conclusion

- New instrumentation for the broadband DC through 220 GHz device and differential IC characterization, including probes, standards, and probe systems
- System integrated solutions developed, including mixer characterization at mmW band
- First results of the broadband measurement metrology solutions, including for the differential DUT

## MTT-S/SCC P2822 Working Group: Join us!

The screenshot shows the IEEE SA Standards Association website. The top navigation bar includes 'Standards', 'Products & Programs', 'Focuses', 'Get Involved', 'Resources', 'MAC ADDRESS', and a search icon. The main content area features a dark header with the title 'P2822 Recommended Practice for Microwave, Millimeter-wave and THz On-Wafer Calibrations, De-Embedding and Measurements'. Below the header, there is a 'Feedback' button on the left and a 'SUBSCRIBE' button on the right. The main text describes the recommended practice, and the 'Sponsor Committee' is listed as 'MTT/SCC - Standards Coordinating Committee'.

Thank you!

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